

Part Number

Customer

Category	Parameter	Specification	Measurement Method	
OverallWafer	1.0	Diameter	150.00 +/- 0.20 mm	
	2.0	Primary Flat Orientation	{110} +/- 0.5 degree	Wafer Vendor
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	None	
	5.0	Overall Thickness	350.00 +/- 5.00 μ m	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<2.00 μ m	Guaranteed by Process
	7.0	Bow	<60.00 μ m	ADE to ASTM F534, 20%
	8.0	Warp	<60.00 μ m	ADE to ASTM F657, 20%
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	3mm	
	11.0	Front Surface Quality	Front side= Prime Optical	
HandleSilicon	12.0	Handle Growth Method	CZ	Wafer Vendor
	13.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor
	14.0	Handle Thickness	350.00 +/- 5.00 μ m	ADE, 100%
	15.0	Handle Doping Type	Any	Wafer Vendor
	16.0	Handle Dopant	Any	Wafer Vendor
	17.0	Handle Resistivity	Any	Wafer Vendor
	18.0	Backside Finish	Polished with light handling marks & Lasermark	Guaranteed by process
	19.0	Backside scratches	Light Handling marks	Bright Light, 100% (note 2)
	20.0	Total scratch length	Frontside - Total <10mm.	Bright Light, 100% (note2)
	21.0	Surface Haze	none	Bright Light, 100% (note 2)
DeviceSilicon	22.0	Top surface Surface Average roughness, Ra	<2A	Guaranteed by process

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Shipping Details	Wafer per box :	Max 25
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness



Explanatory Notes 1. Microscope inspection performed using microscope scan as below. 5x objective.

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information